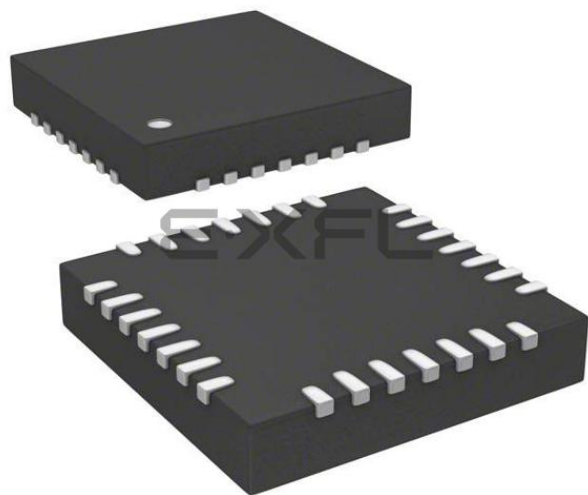




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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	STM8
Core Size	8-Bit
Speed	16MHz
Connectivity	I ² C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, IR, POR, PWM, WDT
Number of I/O	26
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 18x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN
Supplier Device Package	28-UFQFPN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm8l151g6u6

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2.1 Device overview

Table 2. Medium-density STM8L151x4/6 and STM8L152x4/6 low-power device features and peripheral counts

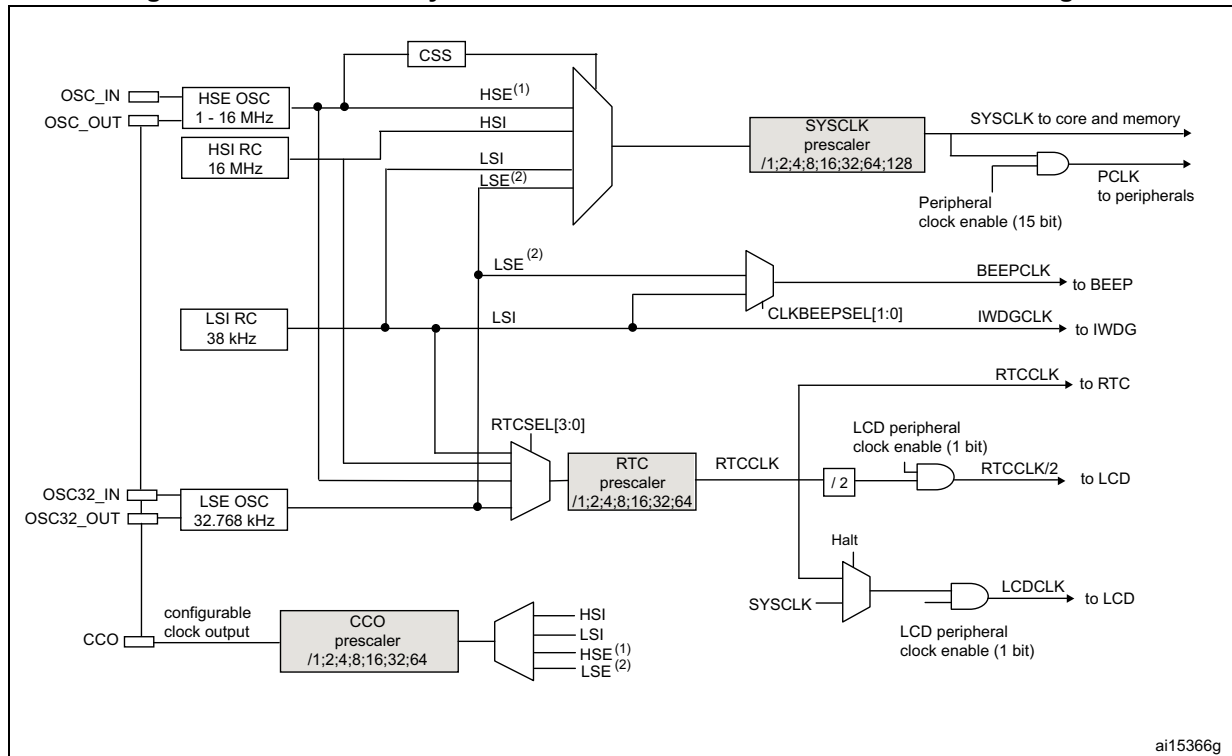
Features		STM8L151Gx		STM8L15xKx		STM8L15xCx	
Flash (Kbyte)		16	32	16	32	16	32
Data EEPROM (Kbyte)		1					
RAM (Kbyte)		2					
LCD		No		4x17 ⁽¹⁾		4x28 ⁽¹⁾	
Timers	Basic	1 (8-bit)					
	General purpose	2 (16-bit)					
	Advanced control	1 (16-bit)					
Communication interfaces	SPI	1					
	I2C	1					
	USART	1					
GPIOs		26 ⁽³⁾		30 ⁽²⁾⁽³⁾ or 29 ⁽¹⁾⁽³⁾		41 ⁽³⁾	
12-bit synchronized ADC (number of channels)		1 (18)		1 (22 ⁽²⁾ or 21 ⁽¹⁾)		1 (25)	
12-Bit DAC (number of channels)		1 (1)					
Comparators COMP1/COMP2		2					
Others		RTC, window watchdog, independent watchdog, 16-MHz and 38-kHz internal RC, 1- to 16-MHz and 32-kHz external oscillator					
CPU frequency		16 MHz					
Operating voltage		1.8 V to 3.6 V (down to 1.65 V at power down)					
Operating temperature		-40 to +85 °C/ -40 to +105 °C / -40 to +125 °C					
Packages		UFQFPN28 (4x4; 0.6 mm thickness) WLCSP28		LQFP32(7x7) UFQFPN32 (5x5; 0.6 mm thickness)		LQFP48 UFQFPN48 (4x4; 0.6 mm thickness)	

1. STM8L152xx versions only

2. STM8L151xx versions only

3. The number of GPIOs given in this table includes the NRST/PA1 pin but the application can use the NRST/PA1 pin as general purpose output only (PA1).

Figure 2. Medium-density STM8L151x4/6 and STM8L152x4/6 clock tree diagram



1. The HSE clock source can be either an external crystal/ceramic resonator or an external source (HSE bypass). Refer to *Section HSE clock* in the STM8L15x and STM8L16x reference manual (RM0031).
2. The LSE clock source can be either an external crystal/ceramic resonator or a external source (LSE bypass). Refer to *Section LSE clock* in the STM8L15x and STM8L16x reference manual (RM0031).

3.5 Low power real-time clock

The real-time clock (RTC) is an independent binary coded decimal (BCD) timer/counter.

Six byte locations contain the second, minute, hour (12/24 hour), week day, date, month, year, in BCD (binary coded decimal) format. Correction for 28, 29 (leap year), 30, and 31 day months are made automatically.

It provides a programmable alarm and programmable periodic interrupts with wakeup from Halt capability.

- Periodic wakeup time using the 32.768 kHz LSE with the lowest resolution (of 61 μ s) is from min. 122 μ s to max. 3.9 s. With a different resolution, the wakeup time can reach 36 hours
- Periodic alarms based on the calendar can also be generated from every second to every year

3.6 LCD (Liquid crystal display)

The liquid crystal display drives up to 4 common terminals and up to 28 segment terminals to drive up to 112 pixels.

- Internal step-up converter to guarantee contrast control whatever V_{DD} .
- Static 1/2, 1/3, 1/4 duty supported.
- Static 1/2, 1/3 bias supported.
- Phase inversion to reduce power consumption and EMI.
- Up to 4 pixels which can be programmed to blink.
- The LCD controller can operate in Halt mode.

Note: Unnecessary segments and common pins can be used as general I/O pins.

3.7 Memories

The medium-density STM8L151x4/6 and STM8L152x4/6 devices have the following main features:

- Up to 2 Kbyte of RAM
- The non-volatile memory is divided into three arrays:
 - Up to 32 Kbyte of medium-density embedded Flash program memory
 - 1 Kbyte of data EEPROM
 - Option bytes.

The EEPROM embeds the error correction code (ECC) feature. It supports the read-while-write (RWW): it is possible to execute the code from the program matrix while programming/erasing the data matrix.

The option byte protects part of the Flash program memory from write and readout piracy.

3.8 DMA

A 4-channel direct memory access controller (DMA1) offers a memory-to-memory and peripherals-from/to-memory transfer capability. The 4 channels are shared between the following IPs with DMA capability: ADC1, DAC, I2C1, SPI1, USART1, the four Timers.

3.9 Analog-to-digital converter

- 12-bit analog-to-digital converter (ADC1) with 25 channels (including 1 fast channel), temperature sensor and internal reference voltage
- Conversion time down to 1 μ s with $f_{SYSCLK} = 16$ MHz
- Programmable resolution
- Programmable sampling time
- Single and continuous mode of conversion
- Scan capability: automatic conversion performed on a selected group of analog inputs
- Analog watchdog
- Triggered by timer

Figure 6. STM8L151G4, STM8L151G6 WLCSP28 package pinout

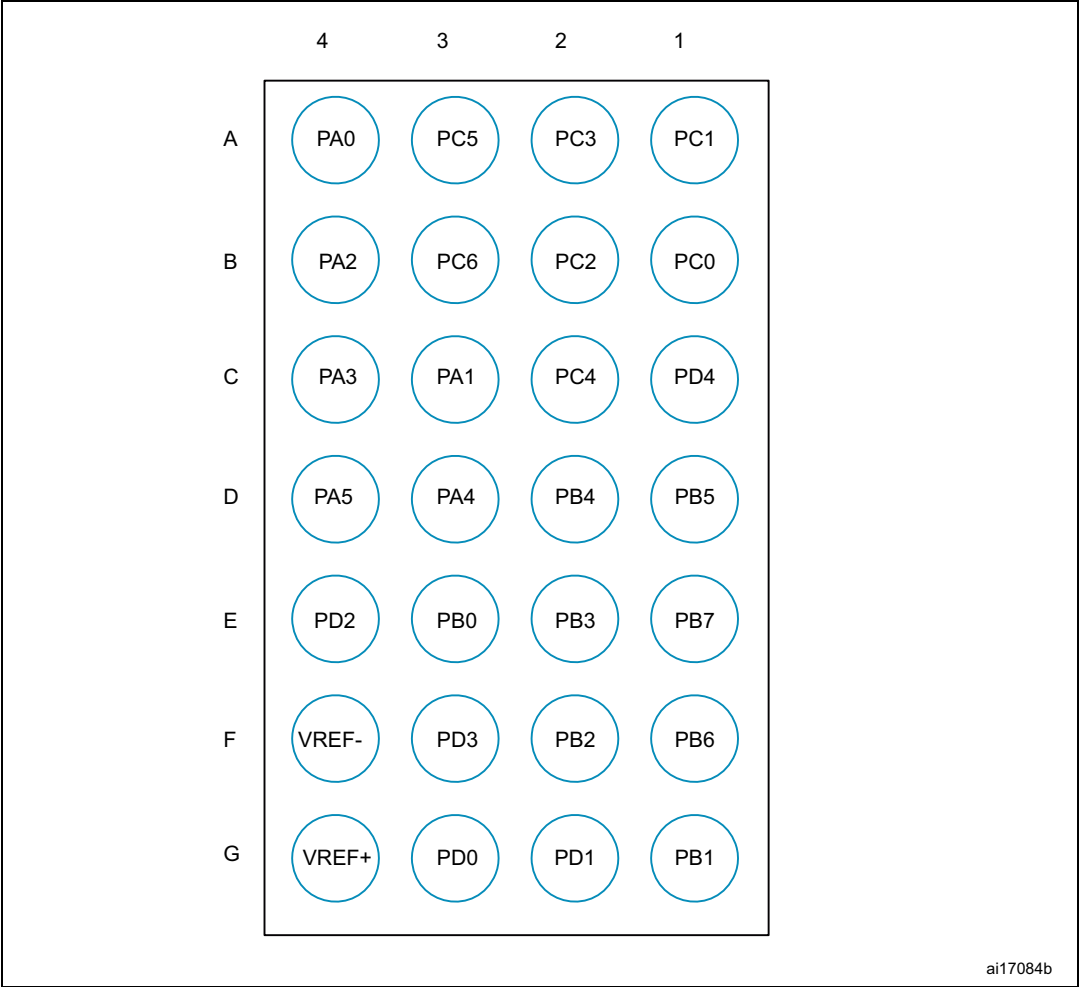


Figure 7. STM8L152C4, STM8L152C6 48-pin pinout (with LCD)

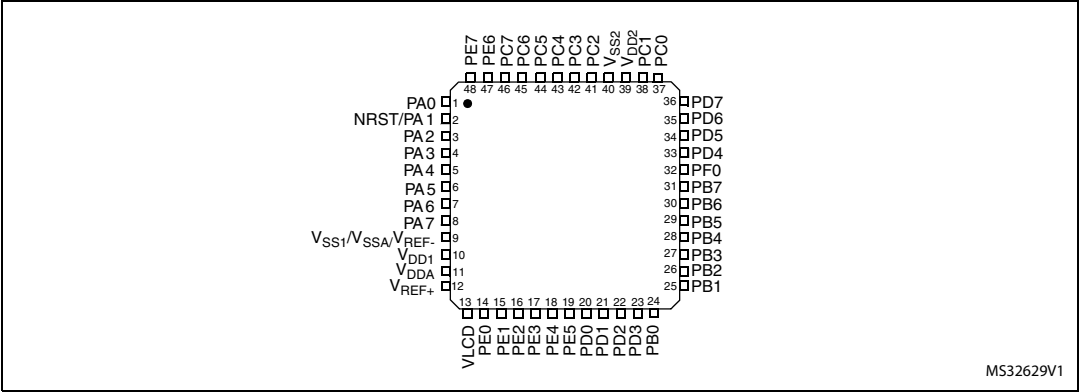


Table 5. Medium-density STM8L151x4/6, STM8L152x4/6 pin description (continued)

Pin number				Pin name	Type	I/O level	Input			Output			Main function (after reset)	Default alternate function
LQFP48/UFQFPN48	LQFP32/UFQFPN32	UFQFPN28	WLCSP28				floating	wpu	Ext. interrupt	High sink/source	OD	PP		
-	16	-	-	PB3/[TIM2_ETR] ⁽⁴⁾ / TIM1_CH2N/LCD_SEG13 (2)/ADC1_IN15/ COMP1_INP	I/O	TT (3)	X	X	X	HS	X	X	Port B3	[Timer 2 - external trigger] / Timer 1 inverted channel 2 / LCD segment 13 / ADC1_IN15 / Comparator 1 positive input
-	-	15	E2	PB3/[TIM2_ETR] ⁽⁴⁾ / TIM1_CH1N/ LCD_SEG13(2)/ ADC1_IN15/RTC_ALARM /COMP1_INP	I/O	TT (3)	X	X	X	HS	X	X	Port B3	[Timer 2 - external trigger] / Timer 1 inverted channel 1 / LCD segment 13 / ADC1_IN15 / RTC alarm / Comparator 1 positive input
28	-	-	-	PB4 ⁽⁶⁾ /[SPI1_NSS] ⁽⁴⁾ / LCD_SEG14(2)/ ADC1_IN14/COMP1_INP	I/O	TT (3)	X ⁽⁶⁾	X ⁽⁶⁾	X	HS	X	X	Port B4	[SPI1 master/slave select] / LCD segment 14 / ADC1_IN14 / Comparator 1 positive input
-	17	16	D2	PB4 ⁽⁶⁾ /[SPI1_NSS] ⁽⁴⁾ / LCD_SEG14(2)/ ADC1_IN14/ COMP1_INP/DAC_OUT	I/O	TT (3)	X ⁽⁶⁾	X ⁽⁶⁾	X	HS	X	X	Port B4	[SPI1 master/slave select] / LCD segment 14 / ADC1_IN14 / DAC output / Comparator 1 positive input
29	-	-	-	PB5/[SPI1_SCK] ⁽⁴⁾ / LCD_SEG15(2)/ ADC1_IN13/COMP1_INP	I/O	TT (3)	X	X	X	HS	X	X	Port B5	[SPI1 clock] / LCD segment 15 / ADC1_IN13 / Comparator 1 positive input
-	18	17	D1	PB5/[SPI1_SCK] ⁽⁴⁾ / LCD_SEG15(2)/ ADC1_IN13/DAC_OUT/ COMP1_INP	I/O	TT (3)	X	X	X	HS	X	X	Port B5	[SPI1 clock] / LCD segment 15 / ADC1_IN13 / DAC output / Comparator 1 positive input

Table 5. Medium-density STM8L151x4/6, STM8L152x4/6 pin description (continued)

Pin number				Pin name	Type	I/O level	Input			Output			Main function (after reset)	Default alternate function
LQFP48/UFQFPN48	LQFP32/UFQFPN32	UFQFPN28	WLCSP28				floating	wpu	Ext. interrupt	High sink/source	OD	PP		
30	-	-	-	PB6/[SPI1_MOSI] ⁽⁴⁾ / LCD_SEG16 ⁽²⁾ / ADC1_IN12/COMP1_INP	I/O	TT (3)	X	X	X	HS	X	X	Port B6	[SPI1 master out/slave in]/ LCD segment 16 / ADC1_IN12 / Comparator 1 positive input
-	19	18	F1	PB6/[SPI1_MOSI] ⁽⁴⁾ / LCD_SEG16 ⁽²⁾ / ADC1_IN12/COMP1_INP/ DAC_OUT	I/O	TT (3)	X	X	X	HS	X	X	Port B6	[SPI1 master out]/ slave in / LCD segment 16 / ADC1_IN12 / DAC output / Comparator 1 positive input
31	20	19	E1	PB7/[SPI1_MISO] ⁽⁴⁾ / LCD_SEG17 ⁽²⁾ / ADC1_IN11/COMP1_INP	I/O	TT (3)	X	X	X	HS	X	X	Port B7	[SPI1 master in- slave out] / LCD segment 17 / ADC1_IN11 / Comparator 1 positive input
37	25	21	B1	PC0 ⁽⁵⁾ /I2C1_SDA	I/O	FT	X		X		T ⁽⁷⁾		Port C0	I2C1 data
38	26	22	A1	PC1 ⁽⁵⁾ /I2C1_SCL	I/O	FT	X		X		T ⁽⁷⁾		Port C1	I2C1 clock
41	27	23	B2	PC2/USART1_RX/ LCD_SEG22/ADC1_IN6/ COMP1_INP/VREFINT	I/O	TT (3)	X	X	X	HS	X	X	Port C2	USART1 receive / LCD segment 22 / ADC1_IN6 / Comparator 1 positive input / Internal voltage reference output
42	28	24	A2	PC3/USART1_TX/ LCD_SEG23 ⁽²⁾ / ADC1_IN5/COMP1_INP/ COMP2_INM	I/O	TT (3)	X	X	X	HS	X	X	Port C3	USART1 transmit / LCD segment 23 / ADC1_IN5 / Comparator 1 positive input / Comparator 2 negative input
43	29	25	C2	PC4/USART1_CK/ I2C1_SMB/CCO/ LCD_SEG24 ⁽²⁾ / ADC1_IN4/COMP2_INM/ COMP1_INP	I/O	TT (3)	X	X	X	HS	X	X	Port C4	USART1 synchronous clock / I2C1_SMB / Configurable clock output / LCD segment 24 / ADC1_IN4 / Comparator 2 negative input / Comparator 1 positive input

Table 5. Medium-density STM8L151x4/6, STM8L152x4/6 pin description (continued)

Pin number				Pin name	Type	I/O level	Input			Output			Main function (after reset)	Default alternate function
LQFP48/UFQFPN48	LQFP32/UFQFPN32	UFQFPN28	WLCSP28				floating	wpu	Ext. interrupt	High sink/source	OD	PP		
44	30	26	A3	PC5/OSC32_IN / [SPI1_NSS] ⁽⁴⁾ / [USART1_TX] ⁽⁴⁾	I/O		X	X	X	HS	X	X	Port C5	LSE oscillator input / [SPI1 master/slave select] / [USART1 transmit]
45	31	27	B3	PC6/OSC32_OUT / [SPI1_SCK] ⁽⁴⁾ / [USART1_RX] ⁽⁴⁾	I/O		X	X	X	HS	X	X	Port C6	LSE oscillator output / [SPI1 clock] / [USART1 receive]
46	-	-	-	PC7/LCD_SEG25 ⁽²⁾ / ADC1_IN3/COMP2_INM/COMP1_INP	I/O	TT ⁽³⁾	X	X	X	HS	X	X	Port C7	LCD segment 25 / ADC1_IN3/ Comparator negative input / Comparator 1 positive input
20	-	8	G3	PD0/TIM3_CH2 / [ADC1_TRIG] ⁽⁴⁾ / LCD_SEG7 ⁽²⁾ / ADC1_IN22/COMP2_INP/COMP1_INP	I/O	TT ⁽³⁾	X	X	X	HS	X	X	Port D0	Timer 3 - channel 2 / [ADC1_Trigger] / LCD segment 7 / ADC1_IN22 / Comparator 2 positive input / Comparator 1 positive input
-	9	-	-	PD0/TIM3_CH2 / [ADC1_TRIG] ⁽⁴⁾ / ADC1_IN22/COMP2_INP/COMP1_INP	I/O	TT ⁽³⁾	X	X	X	HS	X	X	Port D0 ⁽⁸⁾	Timer 3 - channel 2 / [ADC1_Trigger] / ADC1_IN22 / Comparator 2 positive input / Comparator 1 positive input
21	-	-	-	PD1/TIM3_ETR / LCD_COM3 ⁽²⁾ / ADC1_IN21/COMP2_INP/COMP1_INP	I/O	TT ⁽³⁾	X	X	X	HS	X	X	Port D1	Timer 3 - external trigger / LCD_COM3 / ADC1_IN21 / comparator 2 positive input / Comparator 1 positive input
-	10	-	-	PD1/TIM1_CH3N/[TIM3_ETR] ⁽⁴⁾ / LCD_COM3 ⁽²⁾ / ADC1_IN21/COMP2_INP/COMP1_INP	I/O	TT ⁽³⁾	X	X	X	HS	X	X	Port D1	[Timer 3 - external trigger] / TIM1 inverted channel 3 / LCD_COM3 / ADC1_IN21 / Comparator 2 positive input / Comparator 1 positive input

4.1 System configuration options

As shown in [Table 5: Medium-density STM8L151x4/6, STM8L152x4/6 pin description](#), some alternate functions can be remapped on different I/O ports by programming one of the two remapping registers described in the “Routing interface (RI) and system configuration controller” section in the STM8L15xxx and STM8L16xxx reference manual (RM0031).

Table 9. General hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 5055 to 0x00 506F	Reserved area (27 bytes)			
0x00 5070	DMA1	DMA1_GCSR	DMA1 global configuration & status register	0xFC
0x00 5071		DMA1_GIR1	DMA1 global interrupt register 1	0x00
0x00 5072 to 0x00 5074		Reserved area (3 bytes)		
0x00 5075		DMA1_C0CR	DMA1 channel 0 configuration register	0x00
0x00 5076		DMA1_C0SPR	DMA1 channel 0 status & priority register	0x00
0x00 5077		DMA1_C0NDTR	DMA1 number of data to transfer register (channel 0)	0x00
0x00 5078		DMA1_C0PARH	DMA1 peripheral address high register (channel 0)	0x52
0x00 5079		DMA1_C0PARL	DMA1 peripheral address low register (channel 0)	0x00
0x00 507A		Reserved area (1 byte)		
0x00 507B		DMA1_C0M0ARH	DMA1 memory 0 address high register (channel 0)	0x00
0x00 507C		DMA1_C0M0ARL	DMA1 memory 0 address low register (channel 0)	0x00
0x00 507D to 0x00 507E		Reserved area (2 bytes)		
0x00 507F		DMA1_C1CR	DMA1 channel 1 configuration register	0x00
0x00 5080		DMA1_C1SPR	DMA1 channel 1 status & priority register	0x00
0x00 5081		DMA1_C1NDTR	DMA1 number of data to transfer register (channel 1)	0x00
0x00 5082		DMA1_C1PARH	DMA1 peripheral address high register (channel 1)	0x52
0x00 5083		DMA1_C1PARL	DMA1 peripheral address low register (channel 1)	0x00

Table 9. General hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 5084	DMA1	Reserved area (1 byte)		
0x00 5085		DMA1_C1M0ARH	DMA1 memory 0 address high register (channel 1)	0x00
0x00 5086		DMA1_C1M0ARL	DMA1 memory 0 address low register (channel 1)	0x00
0x00 5087 0x00 5088		Reserved area (2 bytes)		
0x00 5089		DMA1_C2CR	DMA1 channel 2 configuration register	0x00
0x00 508A		DMA1_C2SPR	DMA1 channel 2 status & priority register	0x00
0x00 508B		DMA1_C2NDTR	DMA1 number of data to transfer register (channel 2)	0x00
0x00 508C		DMA1_C2PARH	DMA1 peripheral address high register (channel 2)	0x52
0x00 508D		DMA1_C2PARL	DMA1 peripheral address low register (channel 2)	0x00
0x00 508E		Reserved area (1 byte)		
0x00 508F		DMA1_C2M0ARH	DMA1 memory 0 address high register (channel 2)	0x00
0x00 5090		DMA1_C2M0ARL	DMA1 memory 0 address low register (channel 2)	0x00
0x00 5091 0x00 5092		Reserved area (2 bytes)		
0x00 5093		DMA1_C3CR	DMA1 channel 3 configuration register	0x00
0x00 5094		DMA1_C3SPR	DMA1 channel 3 status & priority register	0x00
0x00 5095		DMA1_C3NDTR	DMA1 number of data to transfer register (channel 3)	0x00
0x00 5096		DMA1_C3PARH_ C3M1ARH	DMA1 peripheral address high register (channel 3)	0x40
0x00 5097		DMA1_C3PARL_ C3M1ARL	DMA1 peripheral address low register (channel 3)	0x00
0x00 5098		Reserved area (1 byte)		
0x00 5099		DMA1_C3M0ARH	DMA1 memory 0 address high register (channel 3)	0x00
0x00 509A		DMA1_C3M0ARL	DMA1 memory 0 address low register (channel 3)	0x00
0x00 509B to 0x00 509D		Reserved area (3 bytes)		
0x00 509E	SYSCFG	SYSCFG_RMPCR1	Remapping register 1	0x00
0x00 509F		SYSCFG_RMPCR2	Remapping register 2	0x00

Table 9. General hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 5280	TIM3	TIM3_CR1	TIM3 control register 1	0x00
0x00 5281		TIM3_CR2	TIM3 control register 2	0x00
0x00 5282		TIM3_SMCR	TIM3 Slave mode control register	0x00
0x00 5283		TIM3_ETR	TIM3 external trigger register	0x00
0x00 5284		TIM3_DER	TIM3 DMA1 request enable register	0x00
0x00 5285		TIM3_IER	TIM3 interrupt enable register	0x00
0x00 5286		TIM3_SR1	TIM3 status register 1	0x00
0x00 5287		TIM3_SR2	TIM3 status register 2	0x00
0x00 5288		TIM3_EGR	TIM3 event generation register	0x00
0x00 5289		TIM3_CCMR1	TIM3 Capture/Compare mode register 1	0x00
0x00 528A		TIM3_CCMR2	TIM3 Capture/Compare mode register 2	0x00
0x00 528B		TIM3_CCER1	TIM3 Capture/Compare enable register 1	0x00
0x00 528C		TIM3_CNTRH	TIM3 counter high	0x00
0x00 528D		TIM3_CNTRL	TIM3 counter low	0x00
0x00 528E		TIM3_PSCR	TIM3 prescaler register	0x00
0x00 528F		TIM3_ARRH	TIM3 Auto-reload register high	0xFF
0x00 5290		TIM3_ARRL	TIM3 Auto-reload register low	0xFF
0x00 5291		TIM3_CCR1H	TIM3 Capture/Compare register 1 high	0x00
0x00 5292		TIM3_CCR1L	TIM3 Capture/Compare register 1 low	0x00
0x00 5293		TIM3_CCR2H	TIM3 Capture/Compare register 2 high	0x00
0x00 5294		TIM3_CCR2L	TIM3 Capture/Compare register 2 low	0x00
0x00 5295		TIM3_BKR	TIM3 break register	0x00
0x00 5296		TIM3_OISR	TIM3 output idle state register	0x00
0x00 5297 to 0x00 52AF	Reserved area (25 bytes)			

Table 9. General hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 52B0	TIM1	TIM1_CR1	TIM1 control register 1	0x00
0x00 52B1		TIM1_CR2	TIM1 control register 2	0x00
0x00 52B2		TIM1_SMCR	TIM1 Slave mode control register	0x00
0x00 52B3		TIM1_ETR	TIM1 external trigger register	0x00
0x00 52B4		TIM1_DER	TIM1 DMA1 request enable register	0x00
0x00 52B5		TIM1_IER	TIM1 Interrupt enable register	0x00
0x00 52B6		TIM1_SR1	TIM1 status register 1	0x00
0x00 52B7		TIM1_SR2	TIM1 status register 2	0x00
0x00 52B8		TIM1_EGR	TIM1 event generation register	0x00
0x00 52B9		TIM1_CCMR1	TIM1 Capture/Compare mode register 1	0x00
0x00 52BA		TIM1_CCMR2	TIM1 Capture/Compare mode register 2	0x00
0x00 52BB		TIM1_CCMR3	TIM1 Capture/Compare mode register 3	0x00
0x00 52BC		TIM1_CCMR4	TIM1 Capture/Compare mode register 4	0x00
0x00 52BD		TIM1_CCER1	TIM1 Capture/Compare enable register 1	0x00
0x00 52BE		TIM1_CCER2	TIM1 Capture/Compare enable register 2	0x00
0x00 52BF		TIM1_CNTRH	TIM1 counter high	0x00
0x00 52C0		TIM1_CNTRL	TIM1 counter low	0x00
0x00 52C1		TIM1_PSCRH	TIM1 prescaler register high	0x00
0x00 52C2		TIM1_PSCRL	TIM1 prescaler register low	0x00
0x00 52C3		TIM1_ARRH	TIM1 Auto-reload register high	0xFF
0x00 52C4		TIM1_ARRL	TIM1 Auto-reload register low	0xFF
0x00 52C5		TIM1_RCR	TIM1 Repetition counter register	0x00
0x00 52C6		TIM1_CCR1H	TIM1 Capture/Compare register 1 high	0x00
0x00 52C7		TIM1_CCR1L	TIM1 Capture/Compare register 1 low	0x00
0x00 52C8		TIM1_CCR2H	TIM1 Capture/Compare register 2 high	0x00
0x00 52C9		TIM1_CCR2L	TIM1 Capture/Compare register 2 low	0x00
0x00 52CA		TIM1_CCR3H	TIM1 Capture/Compare register 3 high	0x00
0x00 52CB		TIM1_CCR3L	TIM1 Capture/Compare register 3 low	0x00
0x00 52CC		TIM1_CCR4H	TIM1 Capture/Compare register 4 high	0x00
0x00 52CD		TIM1_CCR4L	TIM1 Capture/Compare register 4 low	0x00
0x00 52CE		TIM1_BKR	TIM1 break register	0x00
0x00 52CF		TIM1_DTR	TIM1 dead-time register	0x00
0x00 52D0		TIM1_OISR	TIM1 output idle state register	0x00
0x00 52D1		TIM1_DCR1	DMA1 control register 1	0x00

Table 9. General hardware register map (continued)

Address	Block	Register label	Register name	Reset status
0x00 534E	ADC1	ADC1_TRIGR1	ADC1 trigger disable 1	0x00
0x00 534F		ADC1_TRIGR2	ADC1 trigger disable 2	0x00
0x00 5350		ADC1_TRIGR3	ADC1 trigger disable 3	0x00
0x00 5351		ADC1_TRIGR4	ADC1 trigger disable 4	0x00
0x00 5352 to 0x00 537F	Reserved area (46 bytes)			
0x00 5380	DAC	DAC_CR1	DAC control register 1	0x00
0x00 5381		DAC_CR2	DAC control register 2	0x00
0x00 5382 to 0x00 5383		Reserved area (2 bytes)		
0x00 5384		DAC_SWTRIGR	DAC software trigger register	0x00
0x00 5385		DAC_SR	DAC status register	0x00
0x00 5386 to 0x00 5387		Reserved area (2 bytes)		
0x00 5388		DAC_RDHRH	DAC right aligned data holding register high	0x00
0x00 5389		DAC_RDHRL	DAC right aligned data holding register low	0x00
0x00 538A to 0x00 538B		Reserved area (2 bytes)		
0x00 538C		DAC_LDHRH	DAC left aligned data holding register high	0x00
0x00 538D		DAC_LDHRL	DAC left aligned data holding register low	0x00
0x00 538E to 0x00 538F		Reserved area (2 bytes)		
0x00 5390		DAC_DHR8	DAC 8-bit data holding register	0x00
0x00 5391 to 0x00 53AB		Reserved area (27 bytes)		
0x00 53AC		DAC_DORH	DAC data output register high	0x00
0x00 53AD		DAC_DORL	DAC data output register low	0x00
0x00 53AE to 0x00 53FF	Reserved area (82 bytes)			

In the following table, data is based on characterization results, unless otherwise specified.

**Table 22. Total current consumption and timing in Low power run mode
at $V_{DD} = 1.65\text{ V}$ to 3.6 V**

Symbol	Parameter	Conditions ⁽¹⁾			Typ	Max	Unit
$I_{DD(LPR)}$	Supply current in Low power run mode	LSI RC osc. (at 38 kHz)	all peripherals OFF	$T_A = -40\text{ }^{\circ}\text{C}$ to $25\text{ }^{\circ}\text{C}$	5.1	5.4	μA
				$T_A = 55\text{ }^{\circ}\text{C}$	5.7	6	
				$T_A = 85\text{ }^{\circ}\text{C}$	6.8	7.5	
				$T_A = 105\text{ }^{\circ}\text{C}$	9.2	10.4	
				$T_A = 125\text{ }^{\circ}\text{C}$	13.4	16.6	
			with TIM2 active ⁽²⁾	$T_A = -40\text{ }^{\circ}\text{C}$ to $25\text{ }^{\circ}\text{C}$	5.4	5.7	
				$T_A = 55\text{ }^{\circ}\text{C}$	6.0	6.3	
				$T_A = 85\text{ }^{\circ}\text{C}$	7.2	7.8	
				$T_A = 105\text{ }^{\circ}\text{C}$	9.4	10.7	
				$T_A = 125\text{ }^{\circ}\text{C}$	13.8	17	
		LSE ⁽³⁾ external clock (32.768 kHz)	all peripherals OFF	$T_A = -40\text{ }^{\circ}\text{C}$ to $25\text{ }^{\circ}\text{C}$	5.25	5.6	
				$T_A = 55\text{ }^{\circ}\text{C}$	5.67	6.1	
				$T_A = 85\text{ }^{\circ}\text{C}$	5.85	6.3	
				$T_A = 105\text{ }^{\circ}\text{C}$	7.11	7.6	
				$T_A = 125\text{ }^{\circ}\text{C}$	9.84	12	
			with TIM2 active ⁽²⁾	$T_A = -40\text{ }^{\circ}\text{C}$ to $25\text{ }^{\circ}\text{C}$	5.59	6	
				$T_A = 55\text{ }^{\circ}\text{C}$	6.10	6.4	
				$T_A = 85\text{ }^{\circ}\text{C}$	6.30	7	
				$T_A = 105\text{ }^{\circ}\text{C}$	7.55	8.4	
				$T_A = 125\text{ }^{\circ}\text{C}$	10.1	15	

1. No floating I/Os

2. Timer 2 clock enabled and counter running

3. Oscillator bypassed (LSEBYP = 1 in CLK_ECKCR). When configured for external crystal, the LSE consumption ($I_{DD\text{ LSE}}$) must be added. Refer to [Table 32](#)

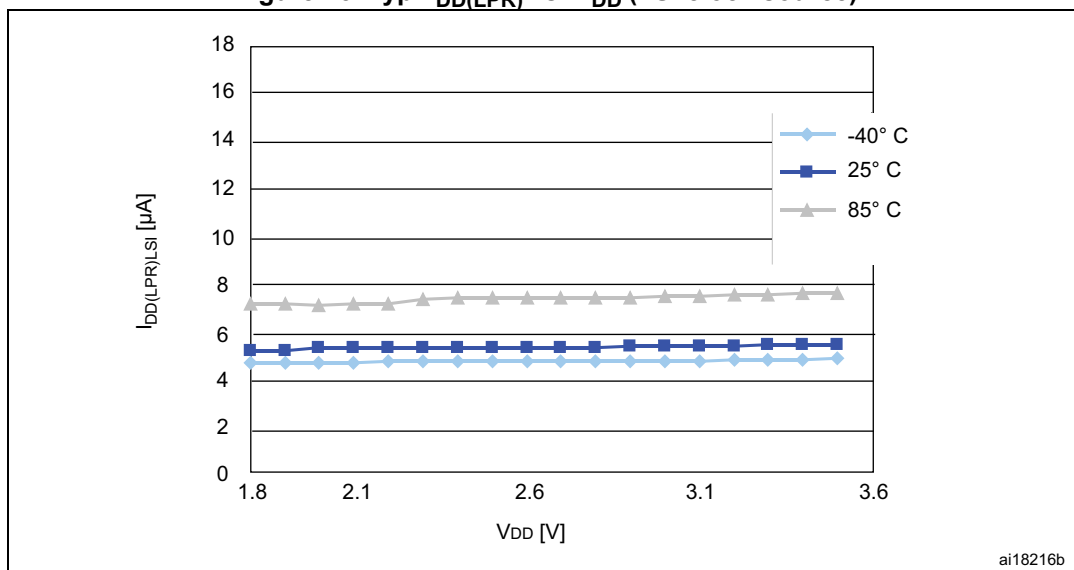
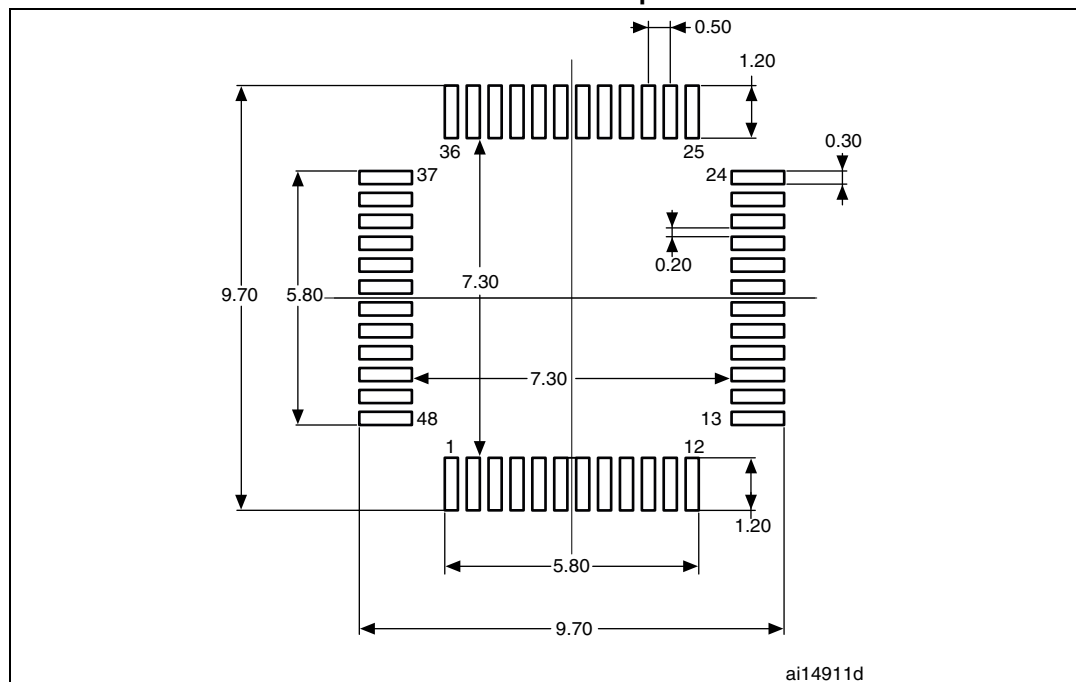
Figure 15. Typ. $I_{DD(LPR)}$ vs. V_{DD} (LSI clock source)

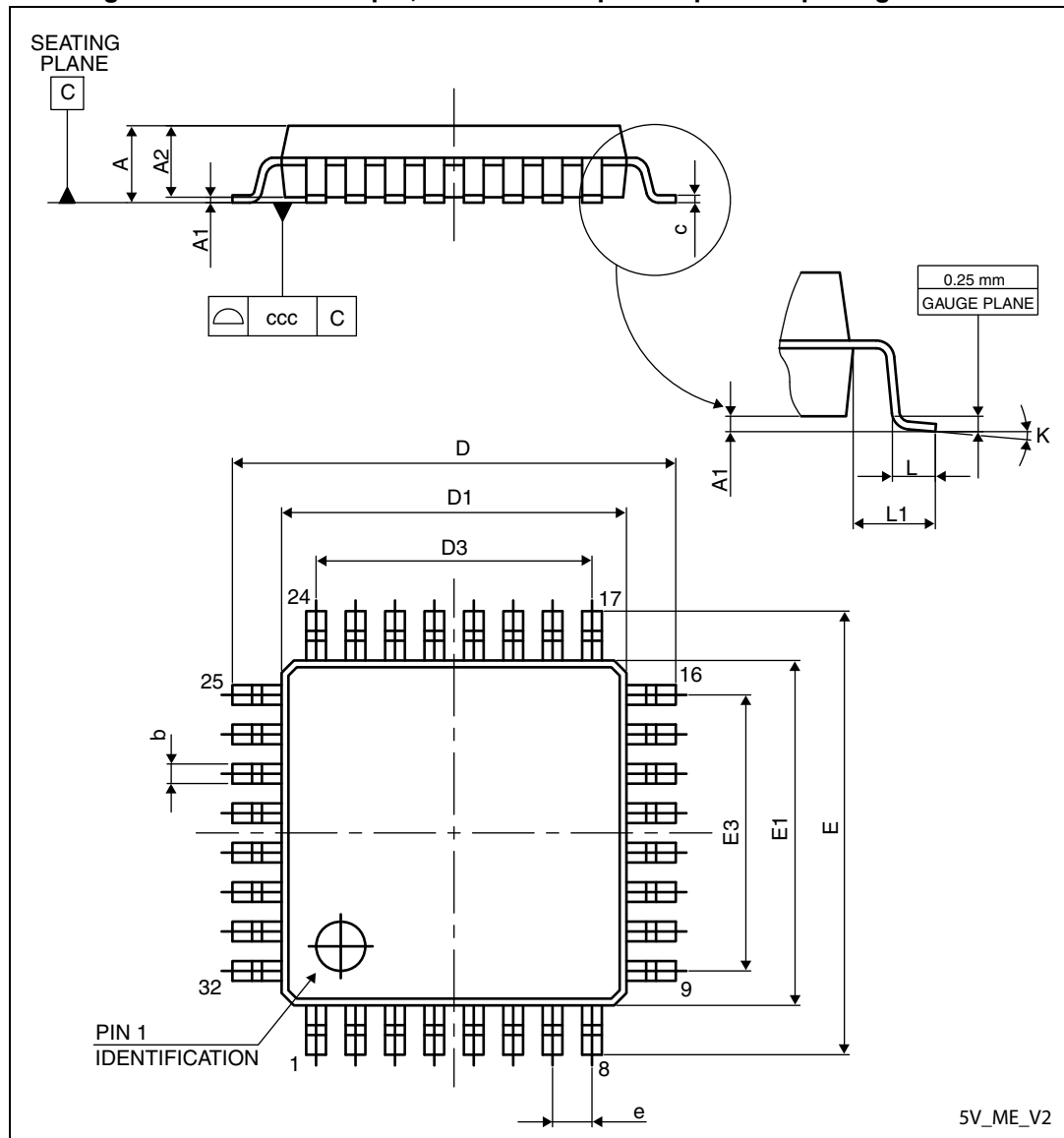
Figure 44. LQFP48 - 48-pin, 7 x 7 mm low-profile quad flat package recommended footprint



1. Dimensions are expressed in millimeters.

10.4 LQFP32 package information

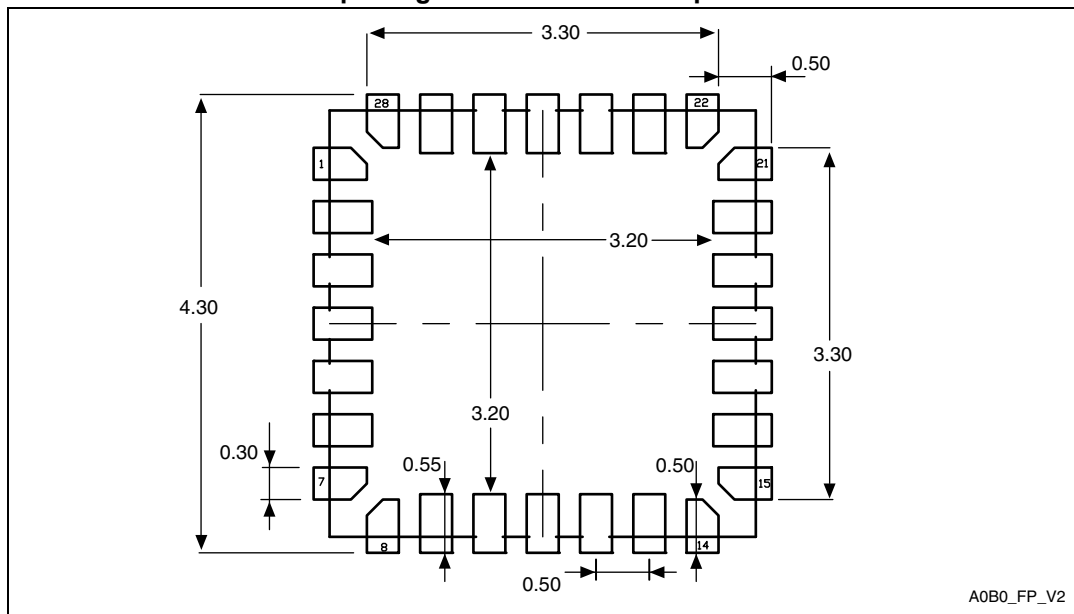
Figure 49. LQFP32 - 32-pin, 7 x 7 mm low-profile quad flat package outline



1. Drawing is not to scale.

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 56. UFQFPN28 - 28-lead, 4 x 4 mm, 0.5 mm pitch, ultra thin fine pitch quad flat package recommended footprint



1. Dimensions are expressed in millimeters.

Table 69. Document revision history (continued)

Date	Revision	Changes
23-Jul-2010	5	Modified <i>Introduction and Description</i>. Modified <i>Table: Legend/abbreviation for table 5</i> and <i>Table: Medium density STM8L15x pin description</i> (for PA0, PA1, PB0 and PB4 and for reset states in the floating input column) Modified <i>Figure: Low density STM8L151xx device block diagram</i>, <i>Figure: Low density STM8L15x clock tree diagram</i>, <i>Figure: Low power modes</i> and <i>Figure: Low power real-time clock</i>. Modified CLK_PCKENR2 and CLK_HSICALR reset values in <i>Table: General hardware register map</i>. Modified notes below <i>Figure: Memory map</i>. Modified PA_CR1 reset value. Modified reset values for Px_IDR registers. Modified <i>Table: Voltage characteristics</i> and <i>Table: Current characteristics</i>. Modified V_{IH} in <i>Table: I/O static characteristics</i>. Modified <i>Table: Total current consumption in Wait mode</i>. Modified <i>Figure Typical application with I2C bus and timing diagram 1</i>). Modified I_L value in <i>Figure: Typical connection diagram using the ADC1</i>. Modified R_H and R_L in <i>Table: LCD characteristics</i>. Added graphs in <i>Section: Electrical parameters</i>. Modified note 3 below <i>Table: Reference voltage characteristics</i>. Modified note 1 below <i>Table: TS characteristics</i>. Changed $V_{ESD(CDM)}$ value in <i>Table: ESD absolute maximum ratings</i>. Updated notes for UFQFPN32 and UFQFPN48 packages.
11-Mar-2011	6	Modified note on true open drain I/Os and I/O level columns in <i>Table: Medium density STM8L15x pin description</i>. Remapping option removed for USART1_TX, USART1_RX, and USART1_CK on PC2, PC3 and PC4 in <i>Table: Medium density STM8L15x pin description</i>. Modified IDWDG_KR reset value in <i>Table: General hardware register map</i>. Replaced VREF_OUT with VREFINT and TIMx_TRIG with TIMx_ETR. Added <i>Table: Factory conversion registers</i>. Modified reset values for TIM1_DCR1, IWDG_KR, RTC_DR1, RTC_DR2, RTC_SPRERH, RTC_SPRERL, RTC_APRER, RTC_WUTRH, and RTC_WUTRL in <i>Table: General hardware register map</i>. Added notes to certain values in <i>Section: Embedded reference voltage</i> and <i>Section: Temperature sensor</i>.